

4 LAYER MULTILAYER BOARD



Production Sequence:-

- 1) a) Photoplot outer and inner layer artworks as negatives
 b) Photoplot Soldermask Artworks (Positives) and Ident Artworks (Negatives) if required.
- 2) CNC Drill Two 3mm Tooling/ Registration holes in inner layer board blank
- 3) Brush clean and dry inner layer blank
- 4) Dry Film laminate inner layer blank
- 5) Align inner layer artworks with tooling holes and tape each side to blank so they cannot move.
- 6) Expose to U.V.
- 7) Conveyorise Develop
- 8) Conveyorise Etch
- 9) Tank Strip Wash and Dry
- 10) Build up multilayer set. Place between press plates and run Heating/Cooling Cycle.
- 11) Remove from Press.
- 12) Place Board Set back on CNC machine locating it on Tooling Pins and Drill all holes.
- 13) Brush Clean
- 14) Through Hole Plate
- 15) Dry Film
- 16) Expose outer layers
- 17) Develop
- 18) Etch
- 19) Strip
- 20) Clean
- 21) Tin



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